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(81) 指定国 (除另有指明, 要求每一种可提供的国家保护): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IR, IS, IT, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW。

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(54) Title: UNLOCKING MECHANISM FOR SEMICONDUCTOR PROCESSING APPARATUS AND SEMICONDUCTOR PROCESSING APPARATUS

(54) 发明名称: 半导体加工设备的开锁机构、半导体加工设备

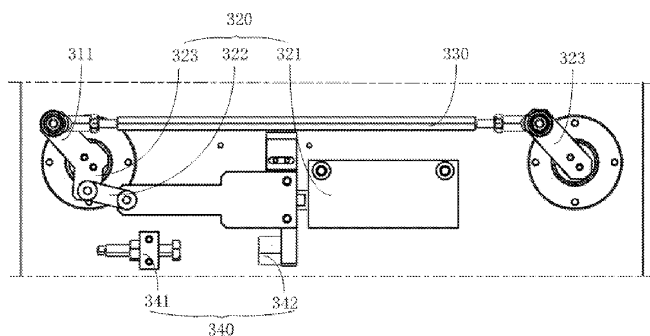


图 6

(57) Abstract: Disclosed in the present application are an unlocking mechanism for a semiconductor processing apparatus and a semiconductor processing apparatus. The unlocking mechanism is used for opening or closing a lock body structure on a sealing door of a chip storage box, and comprises a key and a driving device, wherein the key can move into or out of a key groove of the lock body structure, and matches the key groove in an inserted manner; the driving device is connected to the key and is used for driving the key, when the sealing door is in a closed state, to rotate from an initial position to a first preset position which can enable the sealing door to be in an openable state, and driving the key, when the sealing door is in the openable state, to rotate from the first preset position to a second preset position which can enable the sealing door to be in the closed state; and the driving device is further used for driving the key to rotate from the second preset position to the initial position after the driving device drives the key to rotate from the first preset position to the second preset position, and the key does not make contact with the key groove at the initial position. The above solution can solve the problem that a wafer is easily contaminated during the unlocking process.

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NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), 欧亚 (AM, AZ, BY, KG, KZ, RU, TJ, TM), 欧洲 (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG)。

本国际公布：

- 包括国际检索报告 (条约第21条(3))。

(57) 摘要：本申请公开一种半导体加工设备的开锁机构、半导体加工设备，该开锁机构用于打开或关闭储片盒的密封门上的锁体结构，开锁机构包括钥匙和驱动装置，钥匙能够移入或移出锁体结构的钥匙槽，且钥匙与钥匙槽插接配合；驱动装置与钥匙连接，用于在密封门处于关闭状态时，驱动钥匙自初始位置旋转至能够使密封门处于可开状态的第一预设位置；在密封门处于可开状态时，驱动钥匙自第一预设位置旋转至能够使密封门处于关闭状态的第二预设位置；驱动装置还用于在驱动装置驱动钥匙自第一预设位置旋转至第二预设位置之后，驱动钥匙自第二预设位置旋转至初始位置，钥匙与钥匙槽在初始位置不相接触。上述方案能够解决在开锁过程中容易污染晶圆的问题。